



Docket No.: END920000187US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Hall et al.

Examiner: Dinh, T.

Serial No.: 09/884,778

Art Unit: 2338

Filing Date: 6/19/01

Title: **METHOD AND APPARATUS TO ESTABLISH CIRCUIT LAYERS  
INTERCONNECTIONS**

Commissioner for Patents  
Washington D.C. 20231

**PRELIMINARY AMENDMENT**

Sir:

Prior to examination on the merits, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Claims 21-24 and 27-40 are pending as follows.

21. (Currently Amended) A method of forming a conductive path within a laminate, comprising:

providing an opening in the laminate; [and]

pressing a conductive element into the opening such that a portion of at least one end of the conductive element extends beyond a surface of the laminate; and

applying a compressive pressure to the at least one end of the conductive element.

[wherein a portion of the] whereby the compressive pressure applied to the at least one end of the

